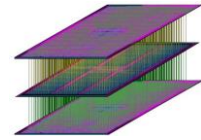




IEEE 3DIC 2021
IEEE International
3D System Integration Conference
Call for Papers
November 15-18, 2021



This year's IEEE International 3D System Integration Conference (3DIC 2021) will be a hybrid physical/virtual event. The live conference will be held at North Carolina State University in Raleigh, NC. The virtual conference will be held concurrently. Authors and attendees can choose either format to interact with 3D researchers from all around the world.

Papers are solicited on all 3D IC topics including, but not limited to, the following:

Technology: Materials, equipment, wafer handling, diverse substrates, Through Silicon Vias (TSV), alignment, bonding (thermo-compression, electrostatic, hybrid, temporary adhesive), de-bonding, wafer cleaning, thinning, dicing, chiplets, interposers (active, passive), 3D integration (monolithic, heterogeneous), capacitive coupling, inductive coupling, multilevel epitaxial growth, etc.

Design and CAD: Synthesis, design flows, signal design, power integrity, thermal considerations, mechanical stress, reliability, test, techniques, analysis, etc. Applications to be considered may include imaging, memory, processors, communications, networking, wireless, biomedical, sensors, SOC, MEMS, DSP, FPGA, RF, microwave, millimeter wave, analog circuits, biomedical circuits, photonics, optoelectronics, etc.

Presentation abstracts may be submitted on the conference website between June 17 and July 31: www.3dic-conf.org. Abstracts should be about 500 words in length; some figures and tables can be included. Notifications will occur by August 31 and full papers in IEEE format will be required by September 30, 2021.

Also soliciting proposals for tutorials, panels, and workshop presentations

Tutorials can be presented virtually or on site. To propose an idea for a tutorial please contact the conference organizers (paulf@ncsu.edu , rpatti@nhanced-semi.com).

Panel discussions may be on-site, virtual, or hybrid. To propose an idea for a panel discussion please contact the conference organizers (paulf@ncsu.edu , rpatti@nhanced-semi.com).

Workshop: A half-day workshop on "Future Directions for 3DIC" will be held on site. This will be for physical attendees only. If you are interested in presenting at the workshop please contact the conference organizers (paulf@ncsu.edu , rpatti@nhanced-semi.com).

Sponsoring Organizations:

IEEE EPS Society

ASET (Associate of Super Advanced Electronics Technologies, Japan)

Sponsoring Institutions:

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Tohoku University

North Carolina State University (NCSU)

2021 Conference Co-Chairs:

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